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Atty. Docket No. CPAC 1017-3  
Appl. No. 10/632,568

MAY 16 2005

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos Karnezos

Application No.: 10/632,568

Filed: Month Day, 2004

Title: Semiconductor multi-package module  
having package stacked over ball grid array  
package and having wire bond interconnect)  
between stacked packages

)  
) Examiner: Douglas M. Menz  
)  
) Group Art Unit: 2824  
)  
) Date: May 16, 2005.

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to  
Examiner Menz in the United States Patent and Trademark Office, at the Central  
Fax no. 703 872-9306 on May 16, 2005.

Signed

Bill Kennedy

COMMISSIONER FOR PATENTS  
P.O Box 1450  
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office action mailed December 15, 2004, kindly amend the application  
as follows.

Amendments to the claims are reflected in the Listing of Claims, which begins on page 2 of this  
paper.

Remarks begin on page 6 of this paper.

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